

PENSARLED®

**HOLISTIC
BROCHURE 2026**

www.pensarled.com



HOLISTIC

Micro Full Flip Chip COB Encapsulation

Holistic pushes beyond conventional color limits with ultra-high grayscale performance and an expanded color gamut. This elevates the viewing experience while leveraging cutting-edge Micro Flip Chip COB technology.

TAA
COMPLIANT

TAA compliance ensures that products are manufactured or substantially transformed in countries approved by U.S. trade agreements. This certification is essential for government, military, and public sector projects, guaranteeing eligibility for federal procurement and compliance with U.S. regulatory standards.

KEY FEATURES

PO.9 – PI.2 – PI.5

- Newest panel of the TFP Series
- Low power and heat
- Flip chip COB
- Low Failure Rate
- Pixel Pitch: 0.9, 1.2, 1.5mm
- Anti-collision, moisture-proof, dust-proof
- Refresh rate: 7680 Hz
- Ultra high contrast: 16,000:1
- High grayscale: 16-24 Bits
- Viewing angle: 160 degrees H/V



The primary benefits of the Holistic Series is the power consumption and heat load. Holistic beats every other manufacture in each of those categories. Holistic is TAA and COO Certified via Taiwan, including the LED Modules.

Low heat load

- 172 BTU/hr max / 58 BTU/hr average

Cabinet depth

- Holistic cabinets are only 1.3" thick

Weight Reduction

- 9.2 lbs per cabinet
- Mount is slim profile stamped steel. Much lighter than the competition

IC Refresh Rate

- IC Refresh Rate - 7680Hz high refresh rate * Double the competition
- Faster processing at the module to eliminate scan lines and improve video quality

High Contrast

- Inking technology combined with COB technology allows for the PCB to be much blacker improving the contrast to 16,000:1

Flip Chip COB (Chip On Board) technology

- Unlike Chip Flip SMD, Chip Flip COB removes an entire layer of encapsulation. This allows chips inside the SMD to be attached directly to the PCB board, removing a major failure point. This improves the overall reliability of the display.



Description	0.9	1.2	1.5
Pixel Pitch (mm)	0.9	1.2	1.5
Led Type	Common Cathode Flip Chip COB		
Module Dimension (WxHxD)	300 x 168.7 mm 11.8 x 6.6 inches	300 x 168.7 mm 11.8 x 6.6 inches	300 x 168.7 mm 11.81 x 6.6 inches
Panel Dimension (WxHxD)	600 x 337.5 x 33 mm 23.6 x 13.2 x 1.2 inches		
Pixel Per Panel	640 x 360	480 x 270	384 x 216
Panel Weight	9.2 lb		
Panel Material	Die-casting Aluminum		
Flatness	≤0.15 mm ≤0.59 inches		
Optical Parameters			
Brightness (nit)	800-1000	800-1000	800-1000
Refresh Rate (Hz)	7680		
Frame Rate (HZ)	Up to 120Hz		
Gray scale (bit)	16-24 Bit		
Contrast Ratio	16,000:1		
Color Temperature (K)	3200 - 9000		
Viewing Angle (H/V) (°)	160/160		
Scan Rate	1/46	1/45	1/46

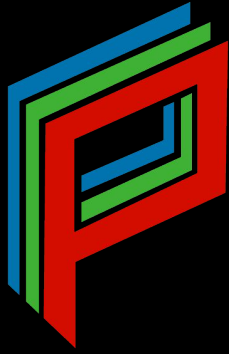
Specifications are subject to change without notice.

Description	0.9	1.2	1.5
Electrical Parameters			
AC Operating Voltage (V)	AC 100~240 (50&60Hz)		
Power Consumption (Max./Avg.)	50/17	50/18	
Application Parameters			
Storage Temperature (F)	-86 ~ +185		
Operating Temperature (F)	-68 ~ +140		
Storage Humidity (RH%)	10 ~ 85%		
Operating Humidity (RH%)	10 ~ 90%		
IP Rating	IP43		
LED Lifetime (H)	100,000		
Maintenance Mode	Front		
Power Supply & Others Maintenance	Front		
Panel Installation Type	Front		
Certification	CE, BSMI CNS15598, FCC, TUV		

***Notes:**

- 1.Power consumption tolerance: $\pm 15\%$
- 2.Panel weight tolerance: $\pm 5\%$
- 3.IP43 : The surface of LDM can be wiped with a damp, soft cloth.

Specifications are subject to change without notice.



PENSARLED®

For more information
federal@pensarled.com

Specifications are subject to change without notice.

www.pensarled.com